



Top View

SOT-223

P3110V

BXXYW

2

VOUT

Top View TO-252

3

N

3

٨N

3

VOUT N

1

GND

1.5A LOW DROPOUT VOLTAGE CMOS REGULATOR

Pin Assignments

1

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Top View

SOT-223

P3110V

AXXYW

2

GND

Top View TO-252

P3110V

2

GND

Top View

P3110V

2

VOUT

1

NIN GND

1

N

3

VOUT

Description

The PAM3110 is a 1.5A CMOS LDO regulator that features a low quiescent current and low dropout voltages, as well as over temperature shutdown. The fixed output voltage of the PAM3110 is set at the factory and trimmed to ±1.5%. The PAM3110 is stable with a ceramic output capacitor of 4.7µF or higher.

This family of regulators can provide either a stand-alone power supply solution or act as a post regulator for switch mode power supplies. They are particularly suitable for applications requiring low input and output voltages.

PAM3110 is available in SOT-223, TO-252 and TO-263-2L package.

Features

- DSP, FPGA and Microprocessor Power Supplies •
- Output Voltages: 1.2V, 1.5V, 1.8V, 2.5V 3.3V and 5.0V •
- Stable with a Ceramic Output Capacitor
- Dropout Voltage: 400mV@1.5A •
- Low Quiescent Current
- Over Temperature Shutdown •
- Short Circuit Protection
- Low Temperature Coefficient
- **Pb-Free Packages**

Applications

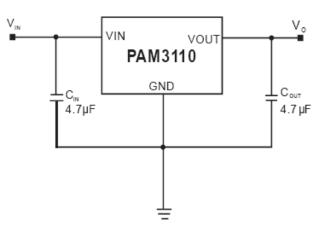
- DSP, FPGA and Microprocessor Power Supplies
- SATA Power Supply
- LCD TV/Monitors
- Wireless Devices
- **Communication Devices**
- Portable Electronics
- Post Regulator for SMS

P3110V AXXYW BXXYW 3 2 1 /OUT VOUT GND Top View TO-263-2L TO-263-2L P3110V AXXYW BXXYW 2 1 3 GND [





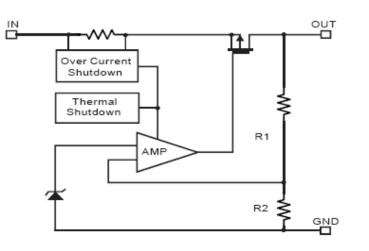
Typical Applications Circuit



Pin Configuration and Description

Din Namo	Pin Name Pin Number SOP-8(EP) W-E		Function	
FIII Name			Function	
VIN	3	7, 8, 9	Supply Input Voltage.	
EN	2	6	ip Enable (Active-High).	
CTRL	4	10	Supply Voltage of ControlCircuitry.	
POK	1	5	Power Good Open Drain Output.	
ADJ	7	4	Set the output voltage by the feedback resistors. $V_0 = 0.8V \times (R1 + R2)/R2$.	
VOUT	6	1, 2, 3	Output Voltage.	
NC	5	—	No Internal Connection.	
GND	8, Exposed Pad (9)	Exposed Pad (11)	Ground. The exposed pad must be soldered to a large PCB and connected to GND formaximum powe r dissipation.	

Functional Block Diagram







Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

These are stress ratings only and functional operation is not implied. Exposure to absolute maximum ratings for prolonged time periods may affect device reliability. All voltages are with respect to ground.

Parameter	Rating	Unit
Input Voltage	6	V
Storage Temperature	-65 to +150	°C
Maximum Junction Temperature	150	°C
Lead Soldering Temperature	300, (5sec)	°C

Recommended Operating Conditions (@T_A = +25°C, unless otherwise specified.)

Parameter	Rating	Unit
Supply Voltage	2.5 to 5.5	V
Ambient Temperature Range	-40 to +85	⊃°C
Junction Temperature Range	-40 to +125	

Thermal Information

Parameter	Symbol	Package	Max	Unit
	θ _{JC}	SOT-223	7	°C/W
Thermal Resistance Junction to Case)		TO-252	7	
		TO-263	7	
	θ _{JA}	SOT-223	160	
Thermal Resistance (Junction to Ambient)		TO-252	90	
		TO-263	60	
		SOT-223	625	
Internal Power Dissipation (@T _A = 25°C)	rer Dissipation (@T _A = 25°C) P _D TO-252 TO-263	1200	mW	
		TO-263	2000]





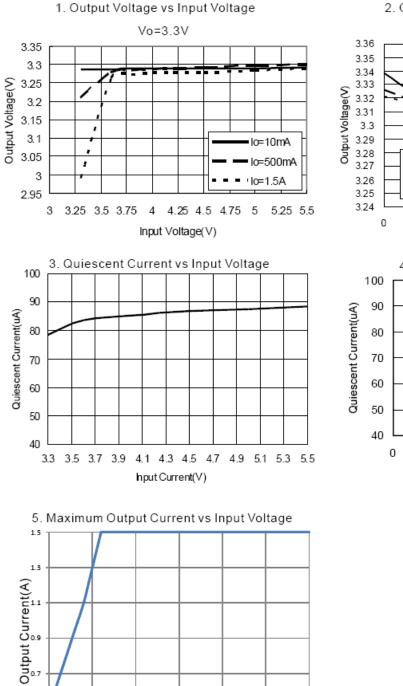
Electrical Characteristics (@T_A = +25°C, V_{IN} = V_O +0.5V, V_{CTRL} = V_{EN} = 5V, C_{IN} = C_O = 10µF, unless otherwise specified.)

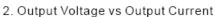
Parameter	Symbol	Test Conditions		Min	Тур	Max	Units
Input Voltage Range	V _{IN}			2.5		5.5	V
Output Voltage Accuracy	Vo	I _O = 1mA to 1.5A		-1.5		1.5	%
Dreneut Valtere	V _{DROP}	I _O = 500mA	V _O ≥ 2.5V		200	mV	
Dropout Voltage		I _O = 1.5A	V _O ≥ 2.5V		400		mv
Short Circuit Current	Isc	V _O < 0.3V			500		mA
Quiescent Current	lq	$I_{O} = 0 \text{mA}$			75	150	μA
Current Limit	I _{LIM}				2		А
	LNR	V _O ≤ 2.5V, I _O = 10mA			0.5	1	%/V
Line Regulation		$V_{IN} = V_{O} + 1.5V$ to $V_{O} + 2.5V$					
		V _O > 2.5V, I _O = 10mA					
		$V_{IN} = V_{O} + 0.5V$ to $V_{O} + 1.5V$					
Load Regulation	LDR	I _O = 1mA to 1.5A			0.5	1	%
Over Temperature Shutdown	OTS				160		°C
Over Temperature Hysteresis	OTH				30		°C
Temperature Coefficient	T _C				40		ppm/°C
			f = 100Hz		55	55	
Power Supply Ripple Rejection	PSRR	I _O = 100mA	f = 1kHz		50		dB
		f = 10kHz			35]	



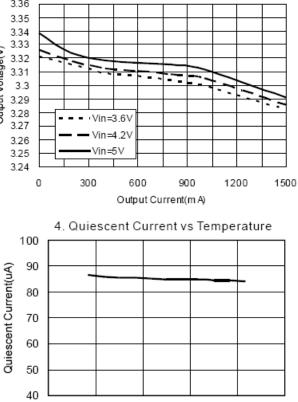


Typical Performance Characteristics (@T_A = +25°C, C_{IN} =4.7µF, C_{OUT} = 4.7µF, unless otherwise specified.)





Vo=3.3V



30

60

90

Tem perature(°C)

120

150

3

3.5

4

Input Voltage(V)

4.5

5

0.5

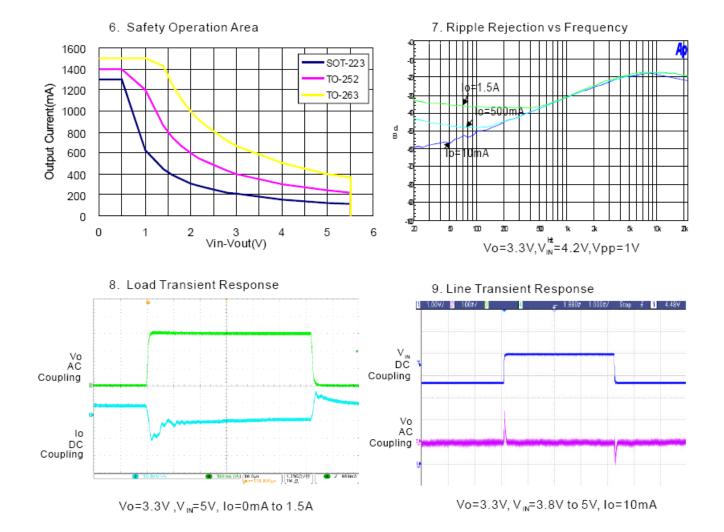
2.5

5.5





Typical Performance Characteristics (cont.) (@T_A = +25°C, C_{IN} =4.7µF, C_{OUT} = 4.7µF, unless otherwise specified.)







Application Information

The PAM3110 family of low-dropout (LDO) regulators have several features that allow them to apply to a wide range of applications. The family operates with very low input voltage and low dropout voltage (typically 300mV at full load), making it an efficient stand-alone power supply or post regulator for battery or switch mode power supplies. The 1.5A output current make the PAM3110 family suitable for powering many microprocessors and FPGA supplies.

External Capacitor Requirements

A 4.7μ F or larger ceramic input bypass capacitor, connected between V_{IN} and GND and located close to the PAM3110, is required for stability. A 4.7μ F minimum value capacitor from V_O to GND is also required. To improve transient response, noise rejection, and ripple rejection, an additional 1 0 μ F or larger, low ESR capacitor is recommended at the output. A higher-value, low ESR output capacitor may be necessary if large, fast-rise-time load transients are anticipated and the device is located several inches from the power source, especially if the minimum input voltage of 2.5V is used.

Regulator Protection

The PAM3110 features internal current limiting, thermal protection and short circuit protection. During normal operation, the PAM3110 limits output current to about 2A. When current limiting engages, the output voltage scales back linearly until the over current condition ends. While current limiting is designed to prevent gross device failure, care should be taken not to exceed the power dissipation ratings of the package. If the temperature of the device exceeds +150°C, thermal-protection circuitry will shut down. Once the device has cooled down to approximately +30°C below the high temp trip point, regulator operation resumes. The short circuit current of the PAM3110 is about 0.5A when its output pin is shorted to ground.

Thermal Information

The amount of heat that an LDO linear regulator generates is:

$$P_{D} = (V_{IN} - V_{O})I_{O}$$

All integrated circuits have a maximum allowable junction temperature ($T_{J(MAX)}$) above which normal operation is not assured. A system designer must design the operating environment so that the operating junction temperature ($T_{J(MAX)}$) does not exceed the maximum junction temperature ($T_{J(MAX)}$). The two main environmental variables that a designer can use to improve thermal performance are air flow and external heat sinks. The purpose of this information is to aid the designer in determining the proper operating environment for a linear regulator that is operating at a specific power level.

In general, the maximum expected power ($P_{D(MAX)}$) consumed by a linear regulator is computed as:

Where:

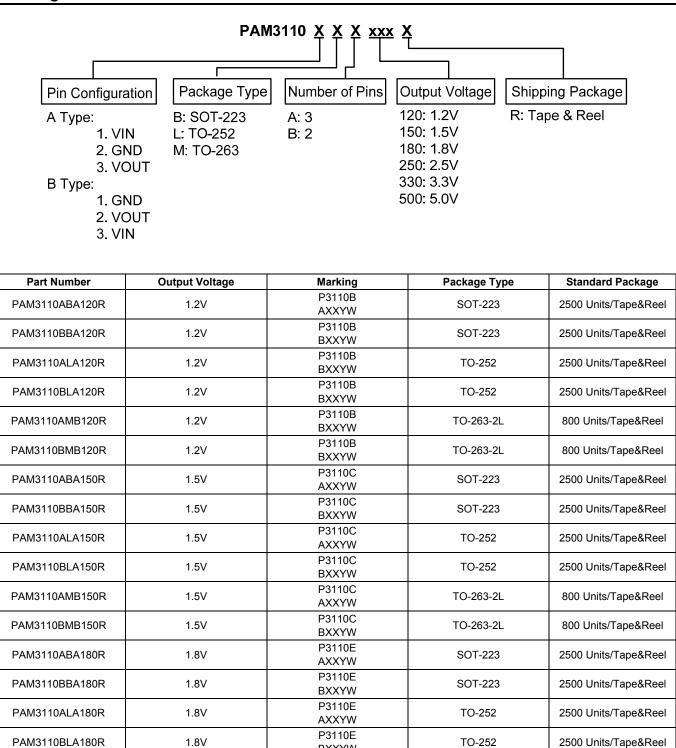
- $\bullet \qquad V_{I(AVG)} \text{ is the average input voltage.}$
- V_{O(AVG)} is the average output voltage.
- I_{O(AVG)} is the average output current.
- I_(Q) is the quiescent current.

For most LDO regulators, the quiescent current is insignificant compared to the average output current; therefore, the term $V_{I(AVG)} \times I_{I(Q)}$ can be neglected. The operating junction temperature is computed by adding the ambient temperature (T_A) and the increase in temperature due to the regulator's power dissipation. The temperature rise is computed by multiplying the maximum expected power dissipation by the sum of the thermal resistances between the junction and the case $R_{\theta JC}$), the case to heatsink ($R_{\theta CS}$), and the heatsink to ambient ($R_{\theta SA}$). Thermal resistances are measures of how effectively an object dissipates heat. Typically, the larger the device, the more surface area available for power dissipation so that the object's thermal resistance will be lowers.





Ordering Information



PAM3110AMB180R

PAM3110BMB180R

1.8V

1.8V

BXXYW P3110E

AXXYW P3110E

BXXYW

TO-263-2L

TO-263-2L

800 Units/Tape&Reel

800 Units/Tape&Reel





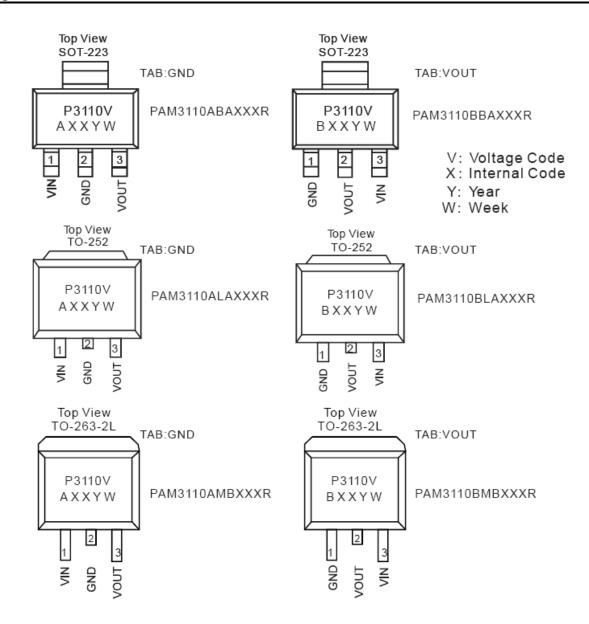
Ordering Information (cont.)

Part Number	Output Voltage	Marking	Package Type	Standard Package	
PAM3110ABA250R	2.5V	P3110G AXXYW	SOT-223	2500 Units/Tape&Reel	
PAM3110BBA250R	2.5V	P3110G BXXYW	SOT-223	2500 Units/Tape&Reel	
PAM3110ALA250R	2.5V	P3110G AXXYW	TO-252	2500 Units/Tape&Reel	
PAM3110BLA250R	2.5V	P3110G BXXYW	TO-252	2500 Units/Tape&Reel	
PAM3110AMB250R	2.5V	P3110G AXXYW	TO-263-2L	800 Units/Tape&Reel	
PAM3110BMB250R	2.5V	P3110G BXXYW	TO-263-2L	800 Units/Tape&Reel	
PAM3110ABR330R	3.3V	P3110K AXXYW	SOT-223	2500 Units/Tape&Reel	
PAM3110BBA330R	3.3V	P3110K BXXYW	SOT-223	2500 Units/Tape&Reel	
PAM3110ALA330R	3.3V	P3110K AXXYW	TO-252	2500 Units/Tape&Reel	
PAM3110BLA330R	3.3V	P3110K BXXYW	TO-252	2500 Units/Tape&Reel	
PAM3110AMB330R	3.3V	P3110K AXXYW	TO-263-2L	800 Units/Tape&Reel	
PAM3110BMB330R	3.3V	P3110K BXXYW	TO-263-2L	800 Units/Tape&Reel	
PAM3110ABA500R	5.0V	P3110L AXXYW	SOT-223	2500 Units/Tape&Reel	
PAM3110BBA500R	5.0V	P3110L BXXYW	SOT-223	2500 Units/Tape&Reel	
PAM3110ALA500R	5.0V	P3110L AXXYW	TO-252	2500 Units/Tape&Reel	
PAM3110BLA500R	5.0V	P3110L BXXYW	TO-252	2500 Units/Tape&Reel	
PAM3110AMB500R	5.0V	P3110L AXXYW	TO-263-2L	800 Units/Tape&Reel	
PAM3110BMB500R	5.0V	P3110L BXXYW	TO-263-2L	800 Units/Tape&Reel	





Marking Information

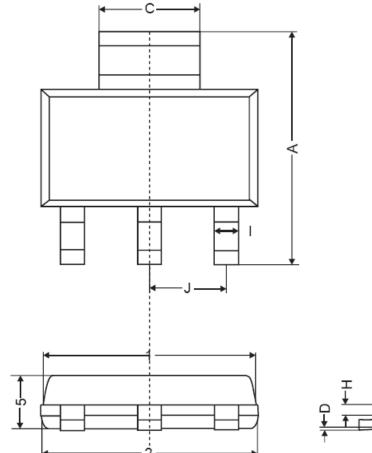




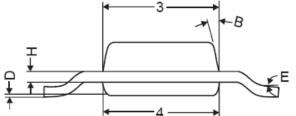


Package Outline Dimensions (All dimensions in mm.)

SOT-223



Dimensions (Millimeter)					
Symbol	MIN	NOM	MAX		
А	6.70	7.00	7.30		
С	2.90	3.00	3.10		
D	0.02	0.06	0.10		
E	0°	5°	10°		
I	0.60	0.70	0.80		
Н	0.25	0.30	0.35		
В	1	3° TYP			
J	2	2.30REF	:		
1	6.30	6.50	6.70		
2	6.30	6.50	6.70		
3	3.30	3.50	3.70		
4	3.30	3.50	3. 70		
5	1.40	1.60	1.80		

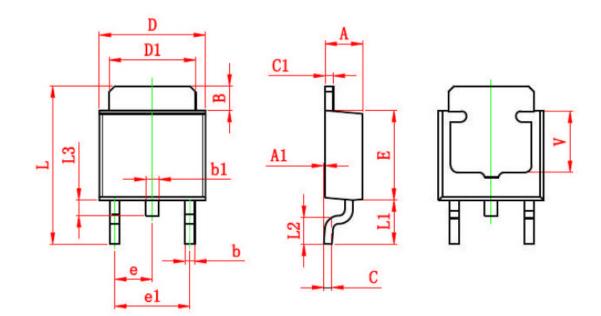






Package Outline Dimensions (cont.) (All dimensions in mm.)

TO-252



Cumhal	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
A	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
В	1.350	1.650	0.053	0.065	
b	0.500	0.700	0.020	0.028	
b1	0.700	0.900	0.028	0.035	
С	0.430	0.580	0.017	0.023	
c1	0.430	0.580	0.017	0.023	
D	6.350	6.650	0.250	0.262	
D1	5.200	5.400	0.205	0.213	
E	5.400	5.700	0.213	0.224	
e	2.300	TYP.	0.091 TYP.		
e1	4.500	4.700	0.177	0.185	
L	9.500	9.900	0.374	0.390	
L1	2.550	2.900	0.100	0.114	
L2	1.400	1.780	0.055	0.070	
L3	0.600	0.900	0.024	0.035	
V	3.800 REF.		0.150 REF.		





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